As an inventor named below or on any attached continuation page, I hereby declare that: My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED, the specification of which (check one):

E is attached hereto							
<ul><li>is attached hereto.</li><li>□ was filed on as</li></ul>	United States	application serial no	and was amended	on			
was filed on as	PCT internat	ional application no	and was amended	under PCT Article 19	on		
I hereby state that I have reviewe arred to above.	d and understa	and the contents of the above	e-identified specification,	including the claims	, as amended by ar	ny amendment	
I acknowledge the duty to disclosimed in this application, as "mate	se to the U.S.	Patent and Trademark Office ined in Title 37, Code of Fed	e all information known t leral Regulations § 1.56.	o me to be material to	the patentability	of the subject matter	
I hereby claim foreign priority b				of any foreign applic	cation(s) for patent	or inventor's	
I hereby claim foreign priority by tifficate or § 365(a) of any PCT in ached continuation page and have international application(s) desirch priority is claimed.	iternational ap	plication(s) designating at it	d continuation page any f	oreign application for	r patent or inventor	r's certificate or any	
or foreign/PCT application(s):					Priority Cla	imed	
200103014-7		Singapore (country)	Ma (day/m	ny 21, 2001 onth/year filed)	X Yes	No	
(number)		(country)	(44)/11	<i></i>			
(number)		(country)	(day/m	onth/year filed)	Yes	No	
I hereby claim the benefit under signating the United States of Ar	r Title 35 Uni	ted States Code, § 120 of an	y United States application	on(s) or § 365(c) of P	CT international a	pplication(s)	
signating the United States of Artication is not disclosed in any stay to disclose to the U.S. Patent a sulations § 1.56 which became a				ational or PCT interna		of this application:	
application serial no.)		(IIIIIg dute)					
(application serial no.)		(filing date)		(status - pending,	patented or aband	oned)	
hereby claim the benefit unde	r Title 35, Un	ited States Code, § 119(e) of	any United States provis	sional application(s) l	isted below:		
(provisional application no.)		(filing date	e)				
7. <b>4.</b> 3							
[] [4] hereby appoint the following	Registered Pro	actitioners to prosecute this a	application and to transac	t all business in the P	atent and Tradema	ark Office connected	
erewith:	Registered 1 to	to prosecution					
		William S. Britt, Reg. No.	o. 20,969	Laurence B. Bond, Reg. No. 30,549 H. Dickson Burton, Reg. No. P-48,396			
Joseph A. Walkowski, Reg. No.	o. 28,765	James R. Duzan, Reg. N. Edgar R. Cataxinos, Reg	o. 28,393 i. No. 39,931	Kent S. Burningham, Reg. No. 30,453			
Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581		Paul C. Oestreich, Reg. 1	No. 44,983	Devin R. Jensen, Re			
Krista Weber Powell, Reg. No.	. 47,867	Jarett K. Abramson, Reg	. No. 47,376	David L. Stott, Reg Bradley B. Jensen,	. No. 43,937 Reg No. 46.801		
Shawn G. Hansen, Reg. No. 4 Katherine A. Hamer, Reg. No.	2,627 47,628	Bretton L. Crockett, Reg Michael L. Lynch, Reg.	No. 30,871	Charles B. Brantley	II, Reg. No. 38,08	36	
Address all correspondence to:	Josep	oh A. Walkowski, telephone	no. (801) 532-1922.				
	P.O. Salt	SKBRITT, PC BOX 2550 Lake City, Utah 84110					
I hereby declare that all statem further that these statements were Section 1001 of Title 18 of the United Section 1001 of Title 18 of Tit	nents made her made with the nited States Co	rein of my own knowledge a e knowledge that willful fals ode and that such willful fals	re true and that all statem e statements and the like se statements may jeopare	ents made on information so made are punishabilize the validity of the	ation and belief are ble by fine or impri e application or an	believed to be true isonment, or both, u y patent issued there	
Full name of first joint inventor: Chon Chin Hui Inventor's signature			Date				
Inventor's signature	ore						
Full name of second joint inventor							
Inventor's signature			Date				
Residence: Singapore							

## DECLARATION FOR PATENT APPLICAT

(continuation page)

Invention title: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Inventor name(s) appearing on first declaration page: Chon Chin Hui

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Additional original, first and joint inventor(s):	
Full name of third joint inventor: Jason Pittam Inventor's signature	
Residence: Morgan Hill, California Citizenship: U.S.A. Post Office Address: 16745 Barnell Avenue, Apt. 3, Morgan Hill, California 95037-4922	

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